







User Manual UM5416

DT5790 DPP-PSD

Register Description and Data Format

Rev. 1 - May 5<sup>th</sup>, 2020

#### Purpose of this Manual

The User Manual contains the full description of the DPP-PSD firmware registers for 720 family series. The description is compliant with the DPP-PSD firmware revision **4.17\_131.11**. For future release compatibility check in the firmware history files.

#### **Change Document Record**

Date	Revision	Changes
September 21 <sup>st</sup> , 2016	00	Initial Release
May 5 <sup>th</sup> , 2020	01	Added register Trigger Latency. Modified registers: Acquisition Control, Acquisition Status, Run/Start/Stop Delay, Board Failure Status, Readout Status, Aggregate Number per BLT. Added Chap. DPP-PSD Memory Organization

#### Symbols, abbreviated terms and notation

Analog-to-Digital Converter
ADC & Memory Controller
Data Acquisition
Digital-to-Analog Converter
Direct Current
Digital Pulse Processing
DPP for Charge to Digital Converter
DPP for Pulse Height Analysis
DPP for Pulse Shape Discrimination
Low-Voltage Differential Signal
ReadOut Controller
Universal Serial Bus

#### **Reference Documents**

[RD1] UM1935 - CAENDigitizer User & Reference Manual.

[RD2] GD2827 - How to make coincidences with CAEN digitizers.

[RD3] UM5960 - CoMPASS User Manual.

All CAEN documents can be downloaded at:

www.caen.it/support-services/documentation-area

CAEN S.pA.

Via Vetraia, 11 55049 Viareggio (LU) - ITALY Tel. +39.0584.388.398 Fax +39.0584.388.959 info@caen.it www.caen.it

©CAEN SpA - 2020

#### Disclaimer

No part of this manual may be reproduced in any form or by any means, electronic, mechanical, recording, or otherwise, without the prior written permission of CAEN SpA.

The information contained herein has been carefully checked and is believed to be accurate; however, no responsibility is assumed for inaccuracies. CAEN SpA reserves the right to modify its products specifications without giving any notice; for up to date information please visit www.caen.it.

MADE IN ITALY: We remark that all our boards have been designed and assembled in Italy. In a challenging environment where a competitive edge is often obtained at the cost of lower wages and declining working conditions, we proudly acknowledge that all those who participated in the production and distribution process of our devices were reasonably paid and worked in a safe environment (while this is true for the boards marked "MADE IN ITALY", we cannot guarantee for third-party manufactures).





# Index

Change document record         2           Symbols, abbreviated terms and notation         2           Reference Documents         2           Reference Documents         2           1 Register and Data Format         6           Register Address Map         6           High Voltage VSet         9           High Voltage Ramp Up         11           High Voltage Ramp Down         12           High Voltage Control         14           High Voltage Control         14           High Voltage Status/AG39 Firmware Release         15           High Voltage WMon/Analog In         16           High Voltage WMon/Analog In         16           High Voltage Width         18           Long Gate Width         18           Long Gate Width         18           Long Gate Width         19           Gate Offset         20           Trigger Threshold         21           Fixed Baseline         22           Trigger Inger Width         24           Threshold for the PSD cut         25           PUR-GAP Threshold         26           DPP Algorithm Control         27           Channel in Status         29           AMC E	Purpose of this Manual	2
Reference Documents         2           1 Registers and Data Format         6           Register Address Map         6           High Voltage VSet         9           High Voltage Exet         10           High Voltage Ramp Down         11           High Voltage Ramp Down         12           High Voltage Control         14           High Voltage Status/A639 Firmware Release         15           High Voltage Whon/Analog In         16           High Voltage IMon/Temperature In         17           Short Sate Width         18           Long Gate Width         18           Gate Offset         20           Trigger Threshold         21           Fixed Baseline         22           Trigger Latency         23           Shaped Trigger Width         24           Threshold for the PSD cut         25           PUR-GAP Threshold         26           DPP Algorithm Control         27           Channel n Status         29           DC Offset         31           Board Configuration         32           Aggregate Organization         34           Record Length         35           Number of Events per Aggregate<	Change document record	2
1 Registers and Data Format         6           Register Address Map         6           High Voltage VSet         9           High Voltage Set         10           High Voltage Ramp Up         11           High Voltage Ramp Down         12           High Voltage Romp Down         12           High Voltage Control         14           High Voltage Status/AG39 Firmware Release         15           High Voltage Whon/Analog In         16           High Voltage IMOn/Temperature In         17           Short Gate Width         18           Long Gate Width         19           Gate Offset         20           Trigger Threshold         21           Fixed Baseline         22           Trigger Latency         23           Shaped Trigger Width         24           Threshold for the PSD cut         25           DPA Algorithm Control         25           DPA Algorithm Control         27           Channel n Status         29           AMC Firmware Revision         30           D C Offset         31           Board Configuration         32           Aggregate Organization         34           Record Length <th>Symbols, abbreviated terms and notation</th> <th> 2</th>	Symbols, abbreviated terms and notation	2
Register Address Map         6           High Voltage VSet         9           High Voltage Ramp Up         11           High Voltage Ramp Down         12           High Voltage VMax         13           High Voltage Control         14           High Voltage Status/A639 Firmware Release         15           High Voltage WMon/Analog In         16           High Voltage WMon/Analog In         17           Short Gate Width         18           Long Gate Width         18           Long Gate Width         19           Gate Offset         20           Trigger Threshold         21           Fixed Baseline         22           Trigger Latency         23           Shaped Trigger Width         24           Threshold for the PSD cut         25           PUR-GAP Threshold         26           DPP Algorithm Control         27           Channel n Status         29           AMC Firmware Revision         30           DC Offset         31           Board Configuration         32           Aggregate Organization         34           Record Length         35           Number of Events per Aggregate <t< th=""><th>Reference Documents</th><th> 2</th></t<>	Reference Documents	2
High Voltage VSet       9         High Voltage ISet       10         High Voltage Ramp Up       11         High Voltage Ramp Down       12         High Voltage VMax       13         High Voltage VMax       13         High Voltage Status/A639 Firmware Release       15         High Voltage WMon/Analog In       16         High Voltage IMon/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       30         Board Configuration       32         Aggregate Organization       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       41 <tr< td=""><td>1 Registers and Data Format</td><td> 6</td></tr<>	1 Registers and Data Format	6
High Voltage Ramp Up       11         High Voltage Ramp Down       12         High Voltage Control       13         High Voltage Control       14         High Voltage Control       14         High Voltage VMon/Analog In       16         High Voltage IMOn/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Control       44 <t< td=""><td>Register Address Map</td><td> 6</td></t<>	Register Address Map	6
High Voltage Ramp Down       12         High Voltage Ramp Down       12         High Voltage Control       14         High Voltage Status/A639 Firmware Release       15         High Voltage IMon/Analog In       16         High Voltage IMon/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Agregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41	High Voltage VSet	9
High Voltage Ramp Down       12         High Voltage Ramp Down       12         High Voltage Control       14         High Voltage Status/A639 Firmware Release       15         High Voltage IMon/Analog In       16         High Voltage IMon/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Agregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41	High Voltage ISet	10
High Voltage Ramp Down       12         High Voltage COntrol       13         High Voltage Control       14         High Voltage Status/A639 Firmware Release       15         High Voltage Won/Analog In       16         High Voltage Width (16)       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Intercy       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         DPA PAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Control       39         Acquisition Control       44 <tr< td=""><td></td><td></td></tr<>		
High Voltage Ontrol       14         High Voltage Control       14         High Voltage Status/AG39 Firmware Release       15         High Voltage WMon/Analog In       16         High Voltage IMon/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42      <		
High Voltage Control       14         High Voltage Status/A639 Firmware Release       15         High Voltage Mon/Analog In       16         High Voltage IMon/Temperature in       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42		
High Voltage Status/A639 Firmware Release       15         High Voltage WMon/Analog In       16         High Voltage IMon/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel TRG-OUT (GPO) Enable Mask <td></td> <td></td>		
High Voltage IMon/Temperature In       16         High Voltage IMon/Temperature In       17         Short Gate Width       18         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel IRG-OUT (GPO) Enable Mask       43         Front Panel IRG-OUT (GPO) Enable Mask       43         Front Panel TRG-OUT for Don triol       44         Channel Enable Mask       46         ROC FPGA Firmware Revi		
High Voltage IMon/Temperature In       17         Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel ING-OUT (GPO) Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49		
Short Gate Width       18         Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50 </td <td></td> <td></td>		
Long Gate Width       19         Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel IRG-OUT (GPO) Enable Mask       43         Front Panel IRG-OUT (GPO) Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/		
Gate Offset       20         Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel IRG-OUT (GPO) Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51 <td< td=""><td></td><td></td></td<>		
Trigger Threshold       21         Fixed Baseline       22         Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel IRG-OUT (GPO) Enable Mask       43         Front Panel Inable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51 <t< td=""><td></td><td></td></t<>		
Fixed Baseline         22           Trigger Latency         23           Shaped Trigger Width         24           Threshold for the PSD cut         25           PUR-GAP Threshold         26           DPP Algorithm Control         27           Channel n Status         29           AMC Firmware Revision         30           DC Offset         31           Board Configuration         32           Aggregate Organization         34           Record Length         35           Number of Events per Aggregate         36           Pre Trigger         37           Trigger Hold-Off Width         38           Acquisition Control         39           Acquisition Status         40           Software Trigger         41           Global Trigger Mask         42           Front Panel TRG-OUT (GPO) Enable Mask         43           Front Panel I/O Control         44           Channel Enable Mask         43           Front Panel I/O Control         44           Channel Enable Mask         46           ROC FPGA Firmware Revision         47           Board Info         48           Event Size         49		
Trigger Latency       23         Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Shaped Trigger Width       24         Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel IRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Threshold for the PSD cut       25         PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       38         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel TRG-OUT (GPO) Enable Mask       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
PUR-GAP Threshold       26         DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
DPP Algorithm Control       27         Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       43         Front Panel Indo       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Channel n Status       29         AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
AMC Firmware Revision       30         DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       8         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
DC Offset       31         Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Board Configuration       32         Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Aggregate Organization       34         Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Record Length       35         Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Number of Events per Aggregate       36         Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Pre Trigger       37         Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Trigger Hold-Off Width       38         Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	· · · · · · · · · · · · · · · · · · ·	
Acquisition Control       39         Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	66	
Acquisition Status       40         Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53		
Software Trigger       41         Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Acquisition Control	39
Global Trigger Mask       42         Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Acquisition Status	40
Front Panel TRG-OUT (GPO) Enable Mask       43         Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Software Trigger	41
Front Panel I/O Control       44         Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Global Trigger Mask	42
Channel Enable Mask       46         ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Front Panel TRG-OUT (GPO) Enable Mask	43
ROC FPGA Firmware Revision       47         Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Front Panel I/O Control	44
Board Info       48         Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	Channel Enable Mask	46
Event Size       49         Fan Speed Control       50         Run/Start/Stop Delay       51         Board Failure Status       52         Disable External Trigger       53	ROC FPGA Firmware Revision	47
Fan Speed Control	Board Info	48
Fan Speed Control	Event Size	
Run/Start/Stop Delay51Board Failure Status52Disable External Trigger53		
Board Failure Status	•	
Disable External Trigger		

	Readout Control	
	Readout Status	_
	Aggregate Number per BLT	
	Scratch	
	Software Reset	
	Software Clear	
	Configuration Reload	
	Configuration ROM Checksum	
	Configuration ROM Checksum Length BYTE 2	
	Configuration ROM Checksum Length BYTE 1	
	Configuration ROM Checksum Length BYTE 0	
	Configuration ROM Constant BYTE 2	
	Configuration ROM Constant BYTE 1	
	Configuration ROM Constant BYTE 0	
	Configuration ROM C Code	
	Configuration ROM R Code	
	Configuration ROM IEEE OUI BYTE 2	
	Configuration ROM IEEE OUI BYTE 1	
	Configuration ROM IEEE OUI BYTE 0	
	Configuration ROM Board Version	
	Configuration ROM Board Form Factor	
	Configuration ROM Board ID BYTE 1	
	Configuration ROM Board ID BYTE 0	
	Configuration ROM PCB Revision BYTE 3	
	Configuration ROM PCB Revision BYTE 2	
	Configuration ROM PCB Revision BYTE 1	
	Configuration ROM PCB Revision BYTE 0	
	Configuration ROM FLASH Type	
	Configuration ROM Board Serial Number BYTE 1	
	Configuration ROM Board Serial Number BYTE 0	
	Configuration ROM VCXO Type	5
2	DPP-PSD Memory Organization	6
_	DT5790 series	
	Event Data Format	
	Channel Aggregate Data Format for DT5790 series	
	Board Aggregate Data Format	
	Data Block	
	•	Ŭ
3	Technical Support	1
ı	ist of Figures	
L	ist of Figures	
	Fig. 2.1 Data organization into the Internal Memory of DT5790	7
	Fig. 2.2 Channel Aggregate Data Format scheme for DT5790 series	8
	Fig. 2.3 Board Aggregate Data Format scheme for DT5790 series	
	<b>Fig. 2.4</b> Data Block scheme	0

## 1 Registers and Data Format

All registers described in the User Manual are 32-bit wide. In case of VME access, **A24** and **A32** addressing mode can be used.

#### Register Address Map

The table below reports the complete list of registers that can be accessed by the user. The register names in the first column can be clicked to be redirected to the relevant register description. The register address is reported on the second column as a hex value. The third column indicates the allowed register access mode, where:

- R **Read only**. The register can be accessed in read only mode.
- W Write only. The register can be accessed in write only mode.
- R/W **Read and write**. The register can be accessed both in read and write mode.

According to the attribute reported in the fourth column, the following choices are available:

Individual register. This kind of register has N instances, where N is the total number of channels in the board. Individual registers can be written either in single mode (individual setting) or broadcast (simultaneous write access to all channels). Read command must be individual.

Single access can be performed at address 0x1nXY, where n is the channel number, while broadcast write can be performed at the address 0x80XY. For example:

- access to address 0x1570 to read/write register 0x1n70 for channel 5 of the board;
- to write the same value for all channels in the board, access to 0x8070 (broadcast write). To read the corresponding value, access to the individual address 0x1n70.
- C Common register. Register with this attribute has a single instance, therefore read and write access can be performed at address 0x80XY only.
- HV register. In case of 780 series and DT5790 some registers manage the HV channels of the boards. Read and write access can be performed at address 0x1nXY only, where n=2 corresponds to the HV channel 0 and n=3 corresponds to the HV channel 1.

Register Name	Address	Mode	Attribute
High Voltage VSet	0x1n20 (n=2 for HV-ch0,	R/W	Н
riigii voitage voet	n=3 for HV-ch1)	11/ 00	"
High Voltage ISet	0x1n24 (n=2 for HV-ch0,	R/W	Н
nigii voitage iset	n=3 for HV-ch1)	I IT/ VV	п п
High Valtage Demon He	0x1n28 (n=2 for HV-ch0,	D /\A/	1.1
High Voltage Ramp Up	n=3 for HV-ch1)	R/W	Н
with the barrier beautiful and the barrier b	0x1n2C (n=2 for HV-ch0,	5 /14/	
High Voltage Ramp Down	n=3 for HV- ch1)	R/W	Н
111 1 11 11 1 1 1 1 1 1 1 1 1 1 1 1 1	0x1n30 (n=2 for HV-ch0,	5/11	
High Voltage VMax	n=3 for HV-ch1)	R/W	Н
	0x1n34 (n=2 for HV-ch0,	- /	
High Voltage Control	n=3 for HV-ch1)	R/W	Н
	0x1n38 (n=2 for HV- ch0,	_	
High Voltage Status/A639 Firmware Release	n=3 for HV-ch1)	R	Н
	0x1n40 (n=2 for HV-ch0,		
High Voltage VMon/Analog In	n=3 for HV-ch1)	R	Н
	0x1n44 (n=2 for HV-ch0,		
High Voltage IMon/Temperature In	n=3 for HV-ch1)	R	Н
Short Gate Width	0x1n54, 0x8054	R/W	ı
Long Gate Width	0x1n58, 0x8058	R/W	i
Gate Offset	0x1n5C, 0x805C	R/W	i
Trigger Threshold	0x1n60, 0x8060	R/W	l
Fixed Baseline	0x1n64, 0x8064	R/W	i
	0x1n6C, 0x8n6C	R/W	l
Trigger Latency	· · · · · · · · · · · · · · · · · · ·	R/W	
Shaped Trigger Width	0x1n70, 0x8070	·	<u> </u>
Threshold for the PSD cut	0x1n78, 0x8078	R/W	l
PUR-GAP Threshold	0x1n7C, 0x807C	R/W	I
DPP Algorithm Control	0x1n80, 0x8080	R/W	I
Channel n Status	0x1n88	R	I
AMC Firmware Revision	0x1n8C	R	I
DC Offset	0x1n98, 0x8098	R/W	I
Board Configuration	0x8000, 0x8004 (BitSet),	R/W	С
	0x8008 (BitClear)	1., 11	Č
Aggregate Organization	0x800C	R/W	С
Record Length	0x8020	R/W	С
Number of Events per Aggregate	0x8034	R/W	С
Pre Trigger	0x8038	R/W	С
Trigger Hold-Off Width	0x8074	R/W	С
Acquisition Control	0x8100	R/W	С
Acquisition Status	0x8104	R	С
Software Trigger	0x8108	W	С
Global Trigger Mask	0x810C	R/W	С
Front Panel TRG-OUT (GPO) Enable Mask	0x8110	R/W	С
Front Panel I/O Control	0x811C	R/W	С
Channel Enable Mask	0x8120	R/W	С
ROC FPGA Firmware Revision	0x8124	R	С
Board Info	0x8140	R	C
Event Size	0x814C	R	С
Fan Speed Control	0x8168	R/W	C
Run/Start/Stop Delay	0x8170	R/W	С
Board Failure Status	0x8178	R	С
Disable External Trigger	0x817C	R/W	С
Trigger Validation Mask	0x8188 (ch0), 0x818C (ch1)	R/W	ı
	0xEF00	R/W	C
	UXLFUU	IN/ VV	L
Readout Control	OveeO4	D	_
Readout Control Readout Status Aggregate Number per BLT	0xEF04 0xEF1C	R R/W	C C

Scratch	0xEF20	R/W	С
Software Reset	0xEF24	W	С
Software Clear	0xEF28	W	С
Configuration Reload	0xEF34	W	С
Configuration ROM Checksum	0xF000	R	С
Configuration ROM Checksum Length BYTE 2	0xF004	R	С
Configuration ROM Checksum Length BYTE 1	0xF008	R	С
Configuration ROM Checksum Length BYTE 0	0xF00C	R	С
Configuration ROM Constant BYTE 2	0xF010	R	С
Configuration ROM Constant BYTE 1	0xF014	R	С
Configuration ROM Constant BYTE 0	0xF018	R	С
Configuration ROM C Code	0xF01C	R	С
Configuration ROM R Code	0xF020	R	С
Configuration ROM IEEE OUI BYTE 2	0xF024	R	С
Configuration ROM IEEE OUI BYTE 1	0xF028	R	С
Configuration ROM IEEE OUI BYTE 0	0xF02C	R	С
Configuration ROM Board Version	0xF030	R	С
Configuration ROM Board Form Factor	0xF034	R	С
Configuration ROM Board ID BYTE 1	0xF038	R	С
Configuration ROM Board ID BYTE 0	0xF03C	R	С
Configuration ROM PCB Revision BYTE 3	0xF040	R	С
Configuration ROM PCB Revision BYTE 2	0xF044	R	С
Configuration ROM PCB Revision BYTE 1	0xF048	R	С
Configuration ROM PCB Revision BYTE 0	0xF04C	R	С
Configuration ROM FLASH Type	0xF050	R	С
Configuration ROM Board Serial Number BYTE 1	0xF080	R	С
Configuration ROM Board Serial Number BYTE 0	0xF084	R	С
Configuration ROM VCXO Type	0xF088	R	С



### High Voltage VSet

Set the channel voltage value (V)

Address 0x1n20 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[15:0]	Channel voltage value in steps of 0.1 V. For example to set 2500 V write 25000.
[31:16]	Reserved

### High Voltage ISet

Set the maximum current limit that can be supplied by a channel

Address 0x1n24 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[15:0]	Set the maximum current in steps of 10 nA (780 series) and 50 nA (DT5790). For example to set 2000 uA, write 40000 for DT5790 and 200000 for 780 series.
[31:16]	Reserved

#### High Voltage Ramp Up

Set the ramp up voltage value in V/s

Address 0x1n28 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[8:0]	Ramp up in V/s.
[31:9]	Reserved

### High Voltage Ramp Down

Set the ramp down voltage value in V/s

Address 0x1n2C (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[8:0]	Ramp down in V/s.
[31:9]	Reserved

#### High Voltage VMax

VMax is the hardware value that can be programmed by the user to limit the maximum voltage of a channel. If a value VSet > VMax is erroneously programmed, the HV channels supplies up to VMax and marks bit[6] of register High Voltage Status 0x1n38.

Address 0x1n30 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
	Maximum voltage value in steps of 20 V for 780 series and DT5790, and 2 V for 780SD boards.
[7:0]	Note: the VMax resolution of 2 V is supported for HV firmware release greater than 2.2. For
	HV firmware release less than 2.2 the VMax resolution is 20 V.
[31:8]	Reserved

### **High Voltage Control**

This register manages the high voltage power and monitor mode

Address 0x1n34 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
	Manages the Power ON/OFF of the HV channel. Options are:
[0]	0: HV channel OFF;
	1: HV channel ON.
	Manages how the channel shuts down. This setting applies both when the user shuts the
	channel down and when the channel automatically shuts down due to an alarm (see register
[1]	High Voltage Status 0x1n38). Options are:
[±]	0: kill mode, the HV channel shuts down instantaneously;
	1: ramp mode, the HV channel shuts down with a rate of V/s as defined by the HV Ramp
	Down register, 0x1n2C.
[6:2]	Reserved
	Manages the monitor mode of the HV channel. Options are:
	0: Register 0x1n40 used to monitor the HV Channel VMon, register 0x1n44 used to monitor
[7]	the HV Channel IMon, register 0x1n38 used to monitor the HV Channel Status;
	1: Register 0x1n40 used to monitor the Analog In, register 0x1n44 used to monitor the
	Temperature In, register 0x1n38 used to monitor the A639 Firmware Release.
[31:8]	Reserved

#### High Voltage Status/A639 Firmware Release

According to the monitor mode value (bit[7] of register High Voltage Control 0x1n34) this register corresponds to:

1. monitor mode = 0, HV channel status (see the bit description for more details). NOTE: in case of bit[3], bit[9], bit[10] or bit[14] = 1 the HV channel is turned off according to Power Down Mode (see HV Channel Control register, 0x1n34);

2. monitor mode = 1, A639 firmware release. For example, for a firmware release 1.03, the register value is 0x103, where 1 corresponds to the register word high byte, and 3 corresponds to the register word low byte.

Address 0x1n38 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[0]	1 = HV power ON
[1]	1 = HV channel rump up
[2]	1 = HV channel rump down
[3]	1 = HV channel is in Over Current (IMon > ISet)
[4]	1 = HV channel is in Over Voltage (VMon > VSet + 2%)
[5]	1 = HV channel is in Under Voltage (VMon < VSet - 2%)
[6]	1 = HV channel is over Maximum Voltage (Vout > VMax)
[7]	1 = HV channel is over Maximum Current (IMon > hardware maximum IOut)
[8]	1 = Temperature warning. The temperature of the HV channel is greater than 80°C.
[9]	1 = Over Temperature. The temperature of the HV channel is greater than 125°C.
[10]	1 = HV channel is disabled for an active external inhibit.
[11]	1 = Calibration error. There is a calibration error on the HV channel.
[12]	1 = Alarm Reset. The HV channel is resetting the alarms.
[13]	1 = HV channel is shutting down
[14]	1 = Maximum Power. The HV output power is greater than 4 W.
[15]	1 = Fan speed high
[31:16]	Reserved

#### High Voltage VMon/Analog In

According to the monitor mode value (bit[7] of register High Voltage Control 0x1n34) this register corresponds to:

- 1. monitor mode = 0, HV channel VMon;
- 2. monitor mode = 1, voltage between Pin 3 (EXT\_ANALOG) and Pin 1 (GND) of the DB9 connector related to the selected channel.

Address 0x1n40 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[15:0]	If monitor mode = 0, these bits read the HV channel VMon. VMon is equal to the content of the register multiplied by the resolution of 0.1 V. For example, if the register value is 10238, VMon = 1023.8 V.  If monitor mode = 1, these bits read the voltage between Pin 3 (EXT_ANALOG) and Pin 1 (GND) of the DB9 connector related to the selected channel. The voltage value is equal to the content of the register multiplied by the inverse of the resolution of 0.001 V.
[31:16]	Reserved

#### High Voltage IMon/Temperature In

According to the monitor mode value (bit[7] of register High Voltage Control 0x1n34) this register corresponds to:

- 1. monitor mode = 0, this register provides the monitored current value;
- 2. monitor mode = 1, this register is used to read the value of the resistance between Pin 8 (EXT\_TEMP) and Pin 1 (GND) of the DB9 connector related to the selected channel.

Address 0x1n44 (n=2 for HV-ch0, n=3 for HV-ch1)

Bit	Description
[15:0]	If monitor mode = 0, these bits provide the monitored current value. The value of Imon is equal to the content of the register multiplied by the resolution (780 series: 10 nA; DT5790: 50 nA). For example, if Imon Reg = 10238 then IMon = 102.38 uA (DT5780). If Imon Reg = 10238 then IMon = 511.9 uA (DT5790). If Monitor Mode = 1, these bits are used to read the value of the resistance between Pin 8 (EXT_TEMP) and Pin 1 (GND) of the DB9 connector related to the selected channel. The resistance value is that of a temperature probe PT100 or PT1000. The resistance value is equal to the content of the register multiplied by the resolution of 0.1 Ohm. For example, if Reg value = 1234, then the resistance value = 123.4 Ohm.
[31:16]	Reserved

#### **Short Gate Width**

Sets the Short Gate width for the charge integration of the fast component in the Pulse Shape Discrimination

Address 0x1n54, 0x8054

Bit	Description
[9:0]	Number of samples for the Short Gate width. Each sample corresponds to 4 ns.
[31:10]	Reserved

#### **Long Gate Width**

Sets the Long Gate width for the charge integration of the slow component in the Pulse Shape Discrimination. The Long integration Gate is also used for the energy spectra calculation

Address 0x1n58, 0x8058

Bit	Description
[13:0]	Number of samples for the Long Gate width. Each sample corresponds to 4 ns.
[31:14]	Reserved

#### **Gate Offset**

To correctly integrate the input pulse, the integration Gate starts before the trigger position. The Gate Offset defines how many samples the Gate starts before the trigger.

Address 0x1n5C, 0x805C

Bit	Description
[7:0]	Number of samples of the Gate Offset. Each sample corresponds to 4 ns.
[31:8]	Reserved



### **Trigger Threshold**

Sets the Trigger Threshold value for the Leading Edge discrimination

Address 0x1n60, 0x8060

Bit	Description
[11:0]	Set the number of LSB counts for the Trigger Threshold, where 1 LSB = 0.49 mV. The threshold is referred to the baseline level.
[31:12]	Reserved

#### **Fixed Baseline**

The baseline calculation can be performed either dynamically or statically. In the first case the user can set the samples of the moving average window through register 0x1n80. In the latter case the user must disable the automatic baseline calculation through bits[22:20] of register 0x1n80 and set the desired value of fixed baseline through this register. The baseline value then remains constant for the whole acquisition.

Note: This register is ignored in case of dynamic calculation.

Address 0x1n64, 0x8064

Bit	Description
[11:0]	Value of Fixed Baseline in LSB counts
[31:12]	Reserved

#### **Trigger Latency**

This register allows the user to set a time window (latency) to be added to the Shaped Trigger Width (i.e. the lenght of the correlation window) required to take into account the latency in the trigger propagation from the piggyback to the motherboard when setting coincidence/anticoincidence between the digitizer channels.

Mandatory values are:

- 0x9 for the x720 (DT5790) and x751 series
- 0x2 for the x725 and x730 series when setting coincidence/anticoincidence within the same channel couple
- 0x9 for the x725 and x730 series when setting coincidence/anticoincidence between channels belonging to different couples.

Address 0x1n6C, 0x8n6C

Bit	Description
[9:0]	Value of the latency in trigger clock cycles, 8 ns step.
[31:10]	Reserved

#### **Shaped Trigger Width**

The Shaped Trigger is a logic signal of programmable width generated by a channel in correspondence to its local self-trigger (that is the output of the leading edge discriminator). It is used to propagate the trigger to the other channels of the board and to other external boards, as well as to feed the coincidence trigger logic.

Address 0x1n70, 0x8070

Bit	Description
[9:0]	Shaped Trigger width in steps of 8 ns.
[31:10]	Reserved

#### Threshold for the PSD cut

Sets the PSD threshold to online select events according to their PSD value. PSD ranges from 0 to 1.

Address 0x1n78, 0x8078

Bit	Description
	Set the PSD threshold value. The desired value has to be multiplied by 1024. For example for
[9:0]	a PSD threshold of 0.12, write 122 (= 0.12 * 1024).
	Set bits[28:27] of register 0x1n80 to enable the cut on gamma or neutron respectively.
[31:10]	Reserved

#### **PUR-GAP Threshold**

A pile-up event is detected when there is a situation of "peak-valley-peak" inside the same gate. The gap between the valley and the peak can be programmed through this register. Refer to the CoMPASS User Manual for additional details.

Address 0x1n7C, 0x807C

Bit	Description
[11:0]	PUR-GAP value in LSB units, where 1 LSB = 0.49 mV.
[31:12]	Reserved

### **DPP Algorithm Control**

Management of the DPP algorithm features

Address 0x1n80, 0x8080

Bit	Description
	Charge Sensitivity: defines how many fC of charge correspond to one channel of the energy
[1:0]	spectrum. Options are:
	00: 40 fC;
	01: 160 fC;
	10: 640 fC;
	11: 2.56 pC.
[3:2]	Reserved
	Charge Pedestal: when enabled a fixed value of 1024 is added to the charge. This feature is
[4]	useful in case of energies close to zero.
	Trigger Counting. Options are:
	0 (default value): the shaped trigger used for TRG-OUT and coincidences reflects only the
	accepted self-triggers, i.e. the real events saved into memory;
[5]	1: the shaped trigger used for TRG-OUT and coincidences reflects all the self- triggers, even
	those of rejected events (for example consecutive events on the same gate, or events
	occurring during the board busy condition).
[6]	Reserved
[0]	Enable Extended Time Stamp. When this option is enabled, additional 15 bits of Time Stamp
	are recorded into the EXTRAS word of the Event Data format. Refer to the CoMPASS User
[7]	Manual for additional details. Also bit[17] of register 0x8000 should be enabled. Options are:
[,]	0: disabled;
	1: enabled.
	Internal Test Pulse. It is possible to enable an internal test pulse for debugging purposes. The
	ADC counts are replaced with the built-in pulse emulator. Options are:
[8]	0: disabled.
	1: enabled.
	Test Pulse Rate. Set the rate of the built-in test pulse emulator. Options are:
	00: 1 kHz;
[10:9]	01: 10 kHz;
[10.5]	10: 100 kHz;
	11: 1 MHz.
[15:11]	Reserved
[13.11]	Pulse Polarity. Options are:
[16]	0: positive pulse;
[16]	1: negative pulse.
[17]	Reserved
[±/]	Trigger Mode. Options are:
	00: Normal mode. Each channel can self-trigger independently from the other channels.
	01: Coincidence mode. Each channel saves the event only when a validation signal occurs
[19:18]	inside the shaped trigger coincidence window.
[15.10]	10: Reserved.
	11: Anti-coincidence mode. Each channel saves the event only when no validation signal
	occurs inside the shaped trigger coincidence window.
[22:20]	Baseline Mean. Sets the number of events for the baseline mean calculation. Options are:
	000: Fixed: the baseline value is fixed to the value set in register 0x1n64;
	001: 8 samples;
	010: 32 samples;
	010: 32 samples; 011: 128 samples;
	other options are reserved.
[23]	Reserved.
ردع	neserveu.

[24]	Disable Self Trigger. When disabled, the self-trigger is still propagated to the mother board for coincidence logic and TRG-OUT front panel connector, though it is not used by the channel to acquire the event. Options are:  0: self-trigger used to acquire and propagated to the trigger logic;  1: self-trigger only propagated to the trigger logic.
[25]	Reserved
[26]	Pile-Up Rejection. Events flagged as pile-up are completely rejected and they are no more available for readout. See the CoMPASS User Manual for additional details. Options are:  0: disabled;  1: enabled.
[27]	Enable PSD cut below threshold (to cut on gammas)
[28]	Enable PSD cut above threshold (to cut on neutrons).
[31:29]	Reserved

#### **Channel n Status**

This register contains the status information of channel n.

Address 0x1n88 Mode R Attribute I

Bit	Description
[1:0]	Reserved.
[2]	If 1, the SPI bus is busy.
[31:3]	Reserved.

#### **AMC Firmware Revision**

Returns the DPP firmware revision (mezzanine level).

To control the mother board firmware revision see register 0x8124.

For example: if the register value is 0xC3218303:

- Firmware Code and Firmware Revision are 131.3;
- Build Day is 21;
- Build Month is March;
- Build Year is 2012.

NOTE: since 2016 the build year started again from 0.

Address 0x1n8C Mode R Attribute I

Bit	Description
[7:0]	Firmware revision number.
[15:8]	Firmware DPP code. Each DPP firmware has a unique code.
[19:16]	Build Day (lower digit).
[23:20]	Build Day (upper digit).
[27:24]	Build Month. For example: 3 means March, 12 is December.
[31:28]	Build Year. For example: 0 means 2000, 12 means 2012. NOTE: since 2016 the build year
	started again from 0.

#### **DC** Offset

This register allows to adjust the baseline position (i.e. the 0 Volt) of the input signal on the ADC scale. The ADC scale ranges from 0 to 2<sup>NBit</sup> - 1, where NBit is the number of bits of the on-board ADC. The DAC controlling the DC Offset has 16 bits, i.e. it goes from 0 to 65535 independently from the NBit value and the board type.

Typically a DC Offset value of 32K (DAC mid-scale) corresponds to about the ADC mid-scale. Increasing values of DC Offset make the baseline decrease. The range of the DAC is about 5% (typ.) larger than the ADC range, hence DAC settings close to 0 and 64K correspond to ADC respectively over and under range.

WARNING: before writing this register, it is necessary to check that bit[2] = 0 at 0x1n88, otherwise the writing process will not run properly!

Address 0x1n98, 0x8098

Bit	Description
[15:0]	DC Offset value in DAC LSB unit.
[31:16]	Reserved.

### **Board Configuration**

This register contains general settings for the board configuration.

Address 0x8000, 0x8004 (BitSet), 0x8008 (BitClear)

Bit	Description
[0]	Reserved: must be 0.
[1]	Reserved: must be 0
[2]	Trigger Propagation: enables the propagation of the individual trigger from mother board
	individual trigger logic to the mezzanine. This is required in case of coincidence trigger mode
[3]	Reserved: must be 0
[4]	Reserved: must be 1.
[7:5]	Reserved: must be 0
[8]	Individual trigger: must be 1
[10:9]	Reserved: must be 0
[11]	Dual Trace: in oscilloscope or mixed mode, it is possible to plot two different waveforms, i.e. the Input and the Baseline. When the dual trace is enabled, the samples of the two signals are interleaved, thus each waveform is recorded at half of the ADC frequency. When disabled only the Input is recorded at the ADC frequency. Options are:  0: disabled; 1: enabled.
[15:12]	Reserved
[16]	Waveform Recording: enables the data recording of the waveform. The user must define the number of samples to be saved in the Record Length (register 0x1n20). According to the Analog Probe option one or two waveforms are saved. Options are:  0: disabled; 1: enabled.
[17]	Extras Recording: when enabled the EXTRAS word is saved into the event data. Refer to the "Channel Aggregate Data Format" chapter below for more details about the EXTRAS word. Options are: 0: disabled; 1: enabled.
[18]	Time Stamp Recording: enables the recording of the time stamp in the Channel Aggregate Data format. Options are: 0: disabled; 1: enabled.
[19]	Charge Recording: enables the recording of the charge in the Channel Aggregate Data format.  Options are: 0: disabled; 1: enabled.
[22:20]	Reserved

	Digital Virtual Probe 3: when the mixed or oscilloscope mode are enabled, the following
	digital virtual probes can be selected:
	000 = "External Trigger";
	001 = "Over Threshold", digital signal that is 1 when the input signal is over the requested
	threshold;
	010 = "Shaped TRG", logic signal of programmable width generated by a channel in
[0= 00]	correspondence with its local self- trigger. It is used to propagate the trigger to the other
[25:23]	channels of the board and to other external boards, as well as to feed the coincidence trigger
	logic;
	011 = "TRG Val. Acceptance Win.", logic signal corresponding to the time window where the
	coincidence validation is accepted. The validation enables the event dump into the memory;
	100 = "Pile Up", logic pulse set to 1 when a pile-up event occurred; 101 = "Coincidence", logic pulse set to 1 when a coincidence occurred;
	110 = Reserved;
	110 - Reserved,
	Digital Virtual Probe 4: when the mixed or oscilloscope mode are enabled, the following
	digital virtual probes can be selected:
	000 = "Short Gate";
	001 = "Over Threshold", digital signal that is 1 when the input signal is over the requested
	threshold;
	010 = "TRG Validation", digital signal that is 1 when a coincidence validation signal comes
[20.26]	from the mother board FPGA;
[28:26]	011 = "TRG HoldOff", logic signal of programmable width generated by a channel in
	correspondence with its local self- trigger. Other triggers are inhibited for the overall Trigger
	Hold-Off duration;
	100 = "Pile Up", logic pulse set to 1 when a pile up event occurred;
	101 = "Coincidence", logic pulse set to 1 when a coincidence occurred;
	110 = Reserved;
	111 = Reserved.
[31:29]	Reserved: must be 0

#### **Aggregate Organization**

The internal memory of the digitizer can be divided into a programmable number of aggregates, where each aggregate contains a specific number of events. This register defines how many aggregates can be contained in the memory. Note: this register must not be modified while the acquisition is running.

Address 0x800C Mode R/W Attribute C

Bit	Description
[3:0]	Aggregate Organization Nb: the number of aggregates is equal to N_aggr = 2 <sup>Nb</sup> . The corresponding values of Nb and N_aggr are:  Nb: N_aggr  0x0 - 0x1: Not used  0x2 : 4  0x3 : 8  0x4 : 16  0x5 : 32  0x6 : 64  0x7 : 128  0x8 : 256  0x9 : 512  0xA : 1024
[31:4]	Reserved: must be 0

#### **Record Length**

Sets the record length for the waveform acquisition

Address 0x8020 Mode R/W Attribute C

Bit	Description
	Number of samples in the waveform according to the formula Ns = N * 8, where Ns is the
[11:0]	record length and N is the register value. For example, write N = 3 to acquire 24 samples.
	Each sample corresponds to 4 ns.
[31:12]	Reserved

# Number of Events per Aggregate

Each channel has a fixed amount of RAM memory to save the events. The memory is divided into a programmable number of buffer, called "aggregates", whose number of events can be programmed by this register.

Address 0x8034 Mode R/W Attribute C

Bit	Description
[9:0]	Number of events per aggregate. Maximum value is 1023.
[31:10]	Reserved

### **Pre Trigger**

The Pre Trigger defines the number of samples before the trigger in the waveform saved into memory.

Address 0x8038 Mode R/W Attribute C

Bit	Description
	Number of samples Ns of the Pre Trigger width. The value is expressed in steps of sampling
[8:0]	frequency (4 ns).
	NOTE: the Pre Trigger value must be greater than the Gate Offset value by at least 32 ns.
[31:9]	Reserved

#### Trigger Hold-Off Width

The Trigger Hold-Off is a logic signal of programmable width generated by a channel in correspondence with its local self- trigger. Other triggers are inhibited for the overall Trigger Hold-Off duration

Address 0x8074 Mode R/W Attribute C

Bit	Description
[9:0]	Set the Trigger Hold-Off width in steps of 8ns.
[31:10]	Reserved.

### **Acquisition Control**

This register manages the acquisition settings.

Address 0x8100 Mode R/W Attribute C

Bit	Description
	Start/Stop Mode Selection (default value is 00).  Options are:  00 = SW CONTROLLED. Start/stop of the run takes place on software command by setting/resetting bit[2] of this register;  01 = S-IN/GPI CONTROLLED (S-IN for VME, GPI for Desktop/NIM). If the acquisition is armed
[1:0]	(i.e. bit[2] = 1), then the acquisition starts when S-IN/GPI is asserted and stops when S-IN/GPI returns inactive. If bit[2] = 0, the acquisition is always off;  10 = FIRST TRIGGER CONTROLLED. If the acquisition is armed (i.e. bit[2] = 1), then the run starts on the first trigger pulse (rising edge on TRG-IN); this pulse is not used as input trigger, while actual triggers start from the second pulse. The stop of Run must be SW controlled (i.e.
	bit[2] = 0); 11 = LVDS CONTROLLED (VME only). It is like option 01 but using LVDS (RUN) instead of S-IN. The LVDS can be set using registers 0x811C and 0x81A0.
[2]	Acquisition Start/Arm (default value is 0).  When bits[1:0] = 00, this bit acts as a Run Start/Stop. When bits[1:0] = 01, 10, 11, this bit arms the acquisition and the actual Start/Stop is controlled by an external signal.  Options are:
	0 = Acquisition STOP (if bits[1:0]=00); Acquisition DISARMED (others); 1 = Acquisition RUN (if bits[1:0]=00); Acquisition ARMED (others).
[3]	Reserved.
[5:4]	Reserved
[6]	PLL Reference Clock Source (Desktop/NIM only). Default value is 0. Options are:
[6]	0 = internal oscillator (50 MHz); 1 = external clock from front panel CLK-IN connector.  NOTE: this bit is reserved in case of VME boards.
[31:7]	Reserved

### **Acquisition Status**

This register monitors a set of conditions related to the acquisition status.

Address 0x8104 Mode R Attribute C

Bit	Description
[1:0]	Reserved.
[2]	Acquisition Status. It reflects the status of the acquisition and drivers the front panel 'RUN' LED.  Options are:  0 = acquisition is stopped ('RUN' is off);  1 = acquisition is running ('RUN' lits).
[3]	Event Ready. Indicates if any events are available for readout.  Options are:  0 = no event is available for readout;  1 = at least one event is available for readout.  NOTE: the status of this bit must be considered when managing the readout from the digitizer.
[4]	Event Full. Indicates if at least one channel has reached the FULL condition.  Options are:  0 = no channel has reached the FULL condition;  1 = the maximum number of events to be read is reached.
[5]	Clock Source. Indicates the clock source status.  Options are:  0 = internal (PLL uses the internal 50 MHz oscillator as reference);  1 = external (PLL uses the external clock on CLK-IN connector as reference).
[6]	Reserved.
[7]	PLL Unlock Detect. This bit flags a PLL unlock condition.  Options are:  0 = PLL has had an unlock condition since the last register read access;  1 = PLL has not had any unlock condition since the last register read access.  NOTE: flag can be restored to 1 via read access to register 0xEF04.
[8]	Board Ready. This flag indicates if the board is ready for acquisition (PLL and ADCs are correctly synchronized).  Options are: 0 = board is not ready to start the acquisition; 1 = board is ready to start the acquisition.  NOTE: this bit should be checked after software reset to ensure that the board will enter immediately in run mode after the RUN mode setting; otherwise, a latency between RUN mode setting and Acquisition start might occur.
[14:9]	Reserved.
[15]	S-IN (VME boards) or GPI (DT/NIM boards) Status. Reads the current logical level on S-IN (GPI) front panel connector.
[16]	TRG-IN Status. Reads the current logical level on TRG-IN front panel connector.
[31:17]	Reserved.



### **Software Trigger**

Writing this register causes a software trigger generation which is propagated to all the enabled channels of the board.

Address 0x8108 Mode W Attribute C

Bit	Description
[31:0]	Write whatever value to generate a software trigger.

# **Global Trigger Mask**

This register sets which signal can contribute to the global trigger generation.

Address 0x810C Mode R/W Attribute C

Bit	Description
	Enables the trigger request from channel 0 to participate to the global trigger logic. Options
[0]	are:
[0]	0 = disabled;
	1 = enabled.
	Enables the trigger request from channel 1 to participate to the global trigger logic. Options
[1]	are:
[+]	0 = disabled;
	1 = enabled.
[19:2]	Reserved
[23:20]	Majority Coincidence Window. Sets the time window for the majority coincidence in units of
[23.20]	the Trigger Clock (8 ns). Majority level must be set different from 0 through bits[26:24].
	Majority Level. Sets the majority level for the global trigger generation. Allowed level values
[26:24]	are 0 and 1. For a level m, the trigger fires when at least m+1 of the trigger requests are
	generated by the enabled channels (bits [1:0]) .
[29:27]	Reserved
	External Trigger. When enabled, the external trigger on TRG-IN participates to the global
	trigger generation in logic OR with the other enabled signals (bit[31] and bits[1:0]).
[30]	Options are:
	0 = disabled;
	1 = enabled.
	Software Trigger. When enabled, the software trigger participates to the global trigger signal
	generation in logic OR with the other enabled signals (bit[30] and bits[1:0]).
[31]	Options are:
	0 = disabled;
	1 = enabled.

# Front Panel TRG-OUT (GPO) Enable Mask

This register sets which signal can contribute to generate the signal on the front panel TRG-OUT LEMO connector (GPO in case of DT and NIM boards).

Address 0x8110 Mode R/W Attribute C

Bit	Description
	Enables the trigger request from channel 0 to participate to the TRG-OUT logic. Options are:
[0]	0 = disabled;
	1 = enabled.
	Enables the trigger request from channel 1 to participate to the TRG-OUT logic. Options are:
[1]	0 = disabled;
	1 = enabled.
[3:2]	Reserved
[7:4]	Reserved
	TRG-OUT (GPO) Generation Logic. The enabled trigger requests can be combined to generate
	the TRG-OUT (GPO) signal.
	Options are:
[9:8]	00 = OR;
	01 = AND;
	10 = Majority;
	11 = Reserved.
	Majority Level. Sets the majority level for the TRG-OUT (GPO) signal generation. Allowed level
[12:10]	values are 0 and 1. For a level m, the trigger fires when at least m+1 of the trigger requests
	are generated by the enabled channels (bits [1:0]) .
[29:13]	Reserved
	External Trigger. When enabled, the external trigger on TRG-IN can participate in the TRG-OUT
	(GPO) signal generation in logic OR with the other enabled signals (bit[31] and bits[1:0]).
[30]	Options are:
	0 = disabled;
	1 = enabled.
	Software Trigger. When enabled, the software trigger can participate in the TRG-OUT (GPO)
	signal generation in logic OR with the other enabled signals (bit[30] and bits[1:0]).
[31]	Options are:
	0 = disabled;
	1 = enabled.

# Front Panel I/O Control

This register manages the front panel I/O connectors. Default value is 0x000000.

Address 0x811C Mode R/W Attribute C

Bit	Description
	LEMO I/Os Electrical Level. This bit sets the electrical level of the front panel LEMO
	connectors: TRG-IN, TRG-OUT (GPO in case of DT and NIM boards), S-IN (GPI in case of DT and
	NIM boards).
[0]	Options are:
	0 = NIM I/O levels;
	1 = TTL I/O levels.
[9:1]	Reserved
	TRG-IN control. The board trigger logic can be synchronized either with the edge of the TRG-IN
	signal, or with its whole duration. Note: this bit must be used in conjunction with bit[11] = 0.
[10]	Options are:
[]	0 = trigger is synchronized with the edge of the TRG-IN signal;
	1 = trigger is synchronized with the whole duration of the TRG-IN signal.
	TRG-IN to Mezzanines (channels).
	Options are:
	0 = TRG-IN signal is processed by the motherboard and sent to mezzanine (default). The
[11]	trigger logic is then synchronized with TRG-IN;
' '	1 = TRG-IN is directly sent to the mezzanines with no mother board processing nor delay. This
	option can be useful when TRG-IN is used to veto the acquisition.
	NOTE: if this bit is set to 1, then bit[10] is ignored.
[13:12]	Reserved.
	Force TRG-OUT (GPO). This bit can force TRG-OUT (GPO in case of DT and NIM boards) test
	logical level if bit[15] = 1.
[14]	Options are:
	0 = Force TRG-OUT (GPO) to 0;
	1 = Force TRG-OUT (GPO) to 1.
	TRG-OUT (GPO) Mode. Options are:
[15]	0 = TRG-OUT (GPO) is an internal signal (according to bits[17:16]);
	1= TRG-OUT (GPO) is a test logic level set via bit[14].
	TRG-OUT (GPO) Mode Selection.
	Options are:
	00 = Trigger: TRG-OUT/GPO propagates the internal trigger sources according to register
	0x8110;
[17:16]	01 = Motherboard Probes: TRG-OUT/GPO is used to propagate signals of the motherboards
	according to bits[19:18];
	10 = Channel Probes: TRG-OUT/GPO is used to propagate signals of the mezzanines (Channel
	Signal Virtual Probe);
	11 = S-IN (GPI) propagation.
	Motherboard Virtual Probe Selection (to be propagated on TRG- OUT/GPO).
	Options are:
	00 = RUN/delayedRUN: this is the RUN in case of ROC FPGA firmware rel. less than 4.12. This
	probe can be selected according to bit[20].
[19:18]	01 = CLKOUT: this clock is synchronous with the sampling clock of the ADC and this option can
	be used to align the phase of the clocks in different boards;
	10 = CLK Phase;
	11 = BUSY/UNLOCK: this is the board BUSY in case of ROC FPGA firmware rel. 4.5 or lower.
	This probe can be selected according to bit[20].

	According to bits[19:18], this bit selects the probe to be propagated on TRG-OUT.
	If bits[19:18] = 00, then bit[20] options are:
	0 = RUN, the signal is active when the acquisition is running and it is synchronized with the
	start run. This option must be used to synchronize the start/stop of the acquisition through
	the TRG-OUT->TR-IN or TRG-OUT->S-IN (GPI) daisy chain.
[20]	1 = delayedRUN. This option can be used to debug the synchronization when the start/stop is
[20]	propagated through the LVDS I/O (VME boards).
	If bits[19:18] = 11, then bit[20] options are:
	0 = Board BUSY;
	1 = PLL Lock Loss.
	NOTE: this bit is reserved in case of ROC FPGA firmware rel. 4.5 or lower.
	NOTE: this bit corresponds to BUSY/UNLOCK for ROC FPGA firmware rel. less than 4.12.
	Pattern Configuration. Configures the information given by the 16-bit PATTERN field in the
	header of the event format (VME only).
[22:21]	Option are:
	00 = PATTERN: 16-bit pattern latched on the 16 LVDS signals as one trigger arrives (default);
	Other options are reserved.
[31:23]	Reserved.

#### **Channel Enable Mask**

This register enables/disables selected channels to participate in the event readout. Disabled channels are not operative.

WARNING: this register must not be modified while the acquisition is running.

Address 0x8120 Mode R/W Attribute C

Bit	Description
	Bit n can enable/disable selected channel n to participate to the event readout. Options are:
[1:0]	0: disabled;
	1: enabled.
[31:2]	Reserved

#### **ROC FPGA Firmware Revision**

This register contains the motherboard FPGA (ROC) firmware revision information.

The complete format is:

Firmware Revision = X.Y (16 lower bits)

Firmware Revision Date = Y/M/DD (16 higher bits)

EXAMPLE 1: revision 3.08, November 12th, 2007 is 0x7B120308. EXAMPLE 2: revision 4.09, March 7th, 2016 is 0x03070409.

NOTE: the nibble code for the year makes this information to roll over each 16 years.

Address 0x8124 Mode R Attribute C

Bit	Description
[7:0]	ROC Firmware Minor Revision Number (Y).
[15:8]	ROC Firmware Major Revision Number (X).
[31:16]	ROC Firmware Revision Date (Y/M/DD).

#### **Board Info**

This register contains the specific information of the board, such as the digitizer family, the channel memory size and the channel density.

Address 0x8140 Mode R Attribute C

Bit	Description
[23:16]	Equipped Channels Number, i.e. 2.
[31:24]	Reserved.

#### **Event Size**

This register contains the current available event size in 32-bit words. The value is updated after a complete readout of each event.

Address 0x814C Mode R Attribute C

Bit	Description
[31:0]	Event Size (32-bit words).

#### **Fan Speed Control**

This register manages the on-board fan speed in order to guarantee an appropriate cooling according to the internal temperature variations.

NOTE: from revision 4 of the motherboard PCB (see register 0xF04C of the Configuration ROM), the automatic fan speed control has been implemented, and it is supported by ROC FPGA firmware revision greater than 4.4 (see register 0x8124)

Independently of the revision, the user can set the fan speed high by setting bit[3] = 1. Setting bit[3] = 0 will restore the automatic control for revision 4 or higher, or the low fan speed in case of revisions lower than 4.

NOTE: this register is supported by Desktop (DT) boards only.

Address 0x8168 Mode R/W Attribute C

Bit	Description
[2:0]	Reserved: Must be 0.
	Fan Speed Mode.
[3]	Options are:
	0 = slow speed or automatic speed tuning;
	1 = high speed.
[5:4]	Reserved: Must be 1.
[31:6]	Reserved: Must be 0.

#### Run/Start/Stop Delay

When the start of Run is given synchronously to several boards connected in Daisy chain, it is necessary to compensate for the delay in the propagation of the Start (or Stop) signal through the chain. This register sets the delay between the arrival of the Start signal at the input of the board (either on S-IN/GPI or TRG- IN) and the actual start of Run. The delay is usually zero for the last board in the chain and rises going backwards along the chain.

Address 0x8170 Mode R/W Attribute C

Bit	Description
[7:0]	Delay value in steps of 16 ns.
[31:8]	Reserved.

#### **Board Failure Status**

This register monitors a set of board errors. In case of a failure, bit[26] in the second word of the event format header is set to 1 during data readout (refer to the digitizer User Manual for event structure description). Reading at this register checks which kind of error occurred.

NOTE: in case of problems with the board, the user is recommended to contact CAEN for support.

Address 0x8178 Mode R Attribute C

Bit	Description
[3:0]	Reserved.
[4]	PLL Lock Loss.
	Options are:
	0 = no error;
	1 = PLL Lock Loss occurred.
[31:5]	Reserved.

#### **Disable External Trigger**

The External Trigger on TRG-IN connector can be disabled through this register. Any functionality related to TRG-IN is disabled as well.

Address 0x817C Mode R/W Attribute C

Bit	Description
	Options are:
[0]	0: external trigger enabled;
	1: external trigger disabled.
[31:1]	Reserved

# **Trigger Validation Mask**

Sets the trigger validation logic

Address 0x8188 (ch0), 0x818C (ch1)

Mode R/W Attribute I

Bit	Description
[3:0]	Sets the trigger request that participates to the generation of the trigger validation signal.  Options are:  0000: reserved;  0010: reserved;  0100: channel 0;  1000: channel 1.
[7:4]	Reserved
[9:8]	Operation Mask. Sets the logic operation among the enabled trigger request signals. Options are:  00: OR;  01: AND;  10: majority;  11: reserved.
[12:10]	Majority Level. Allowed level values are 0 and 1. For a level m, the trigger fires when at least m+1 of the trigger requests are generated by the enabled channels (bits [3:0]).
[29:13]	Reserved
[30]	External Trigger: when enabled the external trigger from TRG-IN front panel connector participates to the trigger validation generation (in logic OR). Options are:  0: disabled;  1: enabled.
[31]	Software Trigger: when enabled the software trigger participates to the trigger validation generation (in logic OR). Options are: 0: disabled; 1: enabled.

#### **Readout Control**

This register is mainly intended for VME boards, anyway some bits are applicable also for DT and NIM boards.

Address 0xEF00 Mode R/W Attribute C

Bit	Description
[2:0]	Reserved
[3]	Optical Link Interrupt Enable.
	Options are:
	0 = Optical Link interrupts are disabled;
	1 = Optical Link interrupts are enabled.
[31:4]	Reserved

#### **Readout Status**

This register contains information related to the readout.

Address 0xEF04 Mode R Attribute C

Bit	Description
[0]	Event Ready. Indicates if there are events stored ready for readout.
	Options are:
[0]	0 = no data ready;
	1 = event ready.
[1]	Reserved.
	Bus Error (VME boards) / Slave-Terminated (DT/NIM boards) Flag.
	Options are:
	0 = no Bus Error occurred (VME boards) or no terminated transfer (DT/NIM boards);
[2]	1 = a Bus Error occurred (VME boards) or one transfer has been terminated by the digitizer in
	consequence of an unsupported register access or block transfer prematurely terminated in
	event aligned readout (DT/NIM).
	NOTE: this bit is reset after register readout at 0xEF04.
[3]	Reserved.
[31:4]	Reserved.

### Aggregate Number per BLT

This register sets the maximum number of complete aggregates which has to be transferred for each block transfer (via VME BLT/CBLT cycles or block readout through Optical Link).

Address 0xEF1C Mode R/W Attribute C

Bit	Description
[9:0]	Number of complete aggregates to be transferred for each block transfer (BLT).
[31:10]	Reserved.

#### Scratch

This register can be used to write/read words for test purposes.

Address 0xEF20 Mode R/W Attribute C

Bit	Description
[31:0]	SCRATCH.

#### **Software Reset**

All the digitizer registers can be set back to their default values on software reset command by writing any value at this register, or by system reset from backplane in case of VME boards.

Address 0xEF24 Mode W Attribute C

Bit	Description
[31:0]	Whatever value written at this location issues a software reset. All registers are set to their
	default values (actual settings are lost).

#### **Software Clear**

All the digitizer internal memories are cleared:

- automatically by the firmware at the start of each run;
- on software command by writing at this register;
- by hardware (VME boards only) through the LVDS interface properly configured.

A clear command does not change the registers actual value, except for resetting the following registers:

- Event Stored;
- Event Size;
- Channel / Group n Buffer Occupancy.

This register resets also the trigger time stamp.

Address 0xEF28 Mode W Attribute C

Bit	Description
[31:0]	Whatever value written at this location generates a software clear.

### **Configuration Reload**

A write access of any value at this location causes a software reset, a reload of Configuration ROM parameters and a PLL reconfiguration.

Address 0xEF34 Mode W Attribute C

Bit	Description
[31:0]	Write whatever value to perform a software reset, a reload of Configuration ROM parameters
[51.0]	and a PLL reconfiguration.

# **Configuration ROM Checksum**

This register contains information on 8-bit checksum of Configuration ROM space.

Address 0xF000 Mode R Attribute C

Bit	Description
[7:0]	Checksum.
[31:8]	Reserved.

#### Configuration ROM Checksum Length BYTE 2

This register contains information on the third byte of the 3-byte checksum length (i.e. the number of bytes in Configuration ROM to checksum).

Address 0xF004 Mode R Attribute C

Bit	Description
[7:0]	Checksum Length: bits[23:16].
[31:8]	Reserved.

#### Configuration ROM Checksum Length BYTE 1

This register contains information on the second byte of the 3-byte checksum length (i.e. the number of bytes in Configuration ROM to checksum).

Address 0xF008 Mode R Attribute C

Bit	Description
[7:0]	Checksum Length: bits[15:8].
[31:8]	Reserved.

### Configuration ROM Checksum Length BYTE 0

This register contains information on the first byte of the 3-byte checksum length (i.e. the number of bytes in Configuration ROM to checksum).

Address 0xF00C Mode R Attribute C

Bit	Description
[7:0]	Checksum Length: bits[7:0].
[31:8]	Reserved.

# **Configuration ROM Constant BYTE 2**

This register contains the third byte of the 3-byte constant.

Address 0xF010 Mode R Attribute C

Bit	Description
[7:0]	Constant: bits[23:16] = 0x83.
[31:8]	Reserved.

# Configuration ROM Constant BYTE 1

This register contains the second byte of the 3-byte constant.

Address 0xF014 Mode R Attribute C

Bit	Description
[7:0]	Constant: bits[15:8] = 0x84.
[31:8]	Reserved.

# Configuration ROM Constant BYTE 0

This register contains the first byte of the 3-byte constant.

Address 0xF018 Mode R Attribute C

Bit	Description
[7:0]	Constant: bits[7:0] = 0x01.
[31:8]	Reserved.

# Configuration ROM C Code

This register contains the ASCII C character code (identifies this as CR space).

Address 0xF01C Mode R Attribute C

Bit	Description
[7:0]	ASCII 'C' Character Code.
[31:8]	Reserved.

# Configuration ROM R Code

This register contains the ASCII R character code (identifies this as CR space).

Address 0xF020 Mode R Attribute C

Bit	Description
[7:0]	ASCII 'R' Character Code.
[31:8]	Reserved.

# **Configuration ROM IEEE OUI BYTE 2**

This register contains information on the third byte of the 3-byte IEEE Organizationally Unique Identifier (OUI).

Address 0xF024 Mode R Attribute C

Bit	Description
[7:0]	IEEE OUI: bits[23:16].
[31:8]	Reserved.

### **Configuration ROM IEEE OUI BYTE 1**

This register contains information on the second byte of the 3-byte IEEE Organizationally Unique Identifier (OUI).

Address 0xF028 Mode R Attribute C

Bit	Description
[7:0]	IEEE OUI: bits[15:8].
[31:8]	Reserved.

# Configuration ROM IEEE OUI BYTE 0

This register contains information on the first byte of the 3-byte IEEE Organizationally Unique Identifier (OUI).

Address 0xF02C Mode R Attribute C

Bit	Description
[7:0]	IEEE OUI: bits[7:0].
[31:8]	Reserved.

# **Configuration ROM Board Version**

This register contains the board version information.

Address 0xF030 Mode R Attribute C

Bit	Description
	Board Version Code. Options for DT5790 are:
[7:0]	DT5790N: 0xD0;
[7.0]	DT5790P: 0xD1;
	DT5790M: 0xD2.
[31:8]	Reserved.

# **Configuration ROM Board Form Factor**

This register contains the information of the board form factor.

Address 0xF034 Mode R Attribute C

Bit	Description
	Board Form Factor CAEN Code.
	Options are:
[7.0]	0x00 = VME64;
[7:0]	0x01 = VME64X;
	0x02 = Desktop;
	0x03 = NIM.
[31:8]	Reserved.

#### **Configuration ROM Board ID BYTE 1**

This register contains the MSB of the 2-byte board identifier.

Address 0xF038 Mode R Attribute C

Bit	Description
[7:0]	Board Number ID: bits[15:8].
[31:8]	Reserved.

# Configuration ROM Board ID BYTE 0

This register contains the LSB information of the 2-byte board identifier.

Address 0xF03C Mode R Attribute C

Bit	Description
[7:0]	Board Number ID: bits[7:0].
[31:8]	Reserved.

#### **Configuration ROM PCB Revision BYTE 3**

This register contains information on the fourth byte of the 4-byte hardware revision.

Address 0xF040 Mode R Attribute C

Bit	Description
[7:0]	PCB Revision: bits[31:24].
[31:8]	Reserved.

#### **Configuration ROM PCB Revision BYTE 2**

This register contains information on the third byte of the 4-byte hardware revision.

Address 0xF044 Mode R Attribute C

Bit	Description
[7:0]	PCB Revision: bits[23:16].
[31:8	Reserved.

#### Configuration ROM PCB Revision BYTE 1

This register contains information on the second byte of the 4-byte hardware revision.

Address 0xF048 Mode R Attribute C

Bit	Description
[7:0]	PCB Revision: bits[15:8].
[31:8]	Reserved.

# Configuration ROM PCB Revision BYTE 0

This register contains information on the first byte of the 4-byte hardware revision.

Address 0xF04C Mode R Attribute C

	Bit	Description
	[7:0]	PCB Revision: bits[7:0].
Γ	[31:8]	Reserved.

# **Configuration ROM FLASH Type**

This register contains information on which FLASH type (storing the FPGA firmware) is present on-board.

Address 0xF050 Mode R Attribute C

Bit	Description
	FLASH Type.
[7.0]	Options are:
[7:0]	0x00 = 8 Mb FLASH;
	0x01 = 32 Mb FLASH.
[31:8]	Reserved.

#### Configuration ROM Board Serial Number BYTE 1

This register contains information on the MSB of the board serial number.

Address 0xF080 Mode R Attribute C

	Bit	Description
ſ	[7:0]	Board Serial Number: bits[15:8].
Γ	[31:8]	Reserved.

#### Configuration ROM Board Serial Number BYTE 0

This register contains information on the LSB of the board serial number.

Address 0xF084 Mode R Attribute C

Bit	Description
[7:0]	Board Serial Number: bits[7:0].
[31:8]	Reserved.

# Configuration ROM VCXO Type

This register contains information on which type of VCXO is present on-board.

Address 0xF088 Mode R Attribute C

Bit	Description
	VCXO Type Code.
	Options for VME Digitizers are:
	0 = AD9510 with 1 GHz;
[31:0]	1 = AD9510 with 500 MHz (not programmable);
	2 = AD9510 with 500 MHz (programmable).
	Options for Desktop/NIM Digitizers are:
	Reserved (value = 0).

# 2 DPP-PSD Memory Organization

Each channel has a fixed amount of RAM memory to save the events. The memory is divided into a programmable number of buffers (also called "aggregates"), where each buffer contains a programmable number of events. The event format is programmable as well. The board registers involved are the following:

- "Aggregate Organization" (Nb), address 0x800C: defines how many aggregates can be contained in the memory (n<sub>aggr</sub> = 2<sup>Nb</sup>).
- "Number of Events per Aggregate" (Ne), address 0x1n34: defines the number of events contained in one aggregate. The maximum allowed value is 1023.
- "Record Length" (Ns), address 0x1n20: defines the number of samples for the waveform acquisition, when enabled (rec len = Ns \* 8).
- "Board Configuration", address 0x8000: defines the acquisition mode and the event data format.



**Note**: Those who need to write their own DAQ software, must take care to choose the Ne value according to the event and buffer size, as explained in the examples in the next section.

Information about the use of these parameters in the CAENDigitizer library can be found in **[RD1]**. According to the programmed event format, an event can contain a certain number of samples of the waveform, one trigger time stamp, the two charges  $Q_{short}$  and  $Q_{long}$ , and the Baseline/Extras information.

#### DT5790 series

The following section describes the structure of the memory organization of DT5790. The physical memory inside the board is made of memory locations, each of 128-bit (16B). In terms of location occupancy:

Trigger Time Stamp = 1 location;

Waveform (if enabled) = 1 location every 8 samples;

Charges (QL and QS) and EXTRAS = 1 location.

Fig. 2.1 shows the data format as saved into the physical memory for DT5790 series.



**Note**: Fig. **2.1** refers to the event storage into the physical memory of the board. Data are then organized in a different format for the event readout. The event readout format is shown in the **Event Data Format** section.

As previously said, the "Record Length" and the "Board Configuration" settings determine the event size; the user must calculate the number of event per buffer (Ne) and the number of buffers ( $2^{Nb}$ ) accordingly. When the board runs in List Mode, the event memory contains only two locations, one for the Trigger Time Tag and one for the Charge and Baseline. Therefore it is very small and it is suggested to use a big value for Ne to make the buffer size as big as at least a few KB. Small buffer size results in low readout bandwidth. The only drawback of setting high values for Ne is that the events are not available for the readout until the buffer is complete; hence there is some latency between the arrival of a trigger and the readout of the relevant event data. Conversely, when the board runs in Oscilloscope Mode, especially when the record length is large, it is more convenient to keep Ne low (typically 1).

Example1: suppose that the mixed mode is enabled and Ns is set to 400 samples:

Event size (in locations) =  $1(\text{Time\_Stamp}) + Ns/8(\text{Waveform}) + 1(\text{Charge\_EXTRA}) = 52 \text{ loc. Suppose to set } Ne = 60 \text{ (number of events per buffer), hence: buffer\_size (in locations) = <math>52 * 60 = 3120 \text{ loc. Supposing that the memory board is made of } 128k \text{ loc./ch, the number of buffers will be: } 128k/3120 = 42 \text{ (buffers)}. This value corresponds to the maximum number of buffers that the memory can contain. However, since the programmable value must be a power of two, the user has to choose the closest number smaller than 42 which can be represented as a power of two, that is <math>2^5 = 32$  (i.e. Nb = 5 has to be written in the "Aggregate Organization" register).

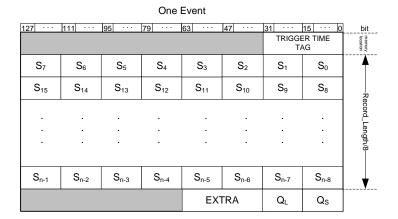


Fig. 2.1: Data organization into the Internal Memory of DT5790.

Example2: suppose that the mixed mode is enabled and Ns is set to 24 samples: Event size (in locations) = 1(Time\_Stamp) + Ns/8(Waveform) + 1(Charge\_EXTRAS) = 5 loc. Having a small event size, it is convenient to divide the memory into few buffers of bigger size to store a large number of events. Suppose to have set Nb = 3, so that the number of buffers is 8. Supposing that the board memory option is made of 64k locations, each buffer consists in 64k/8 = 8k locations and so the resulting number of event per aggregate should be: Ne = 8k/5 = 1639. **IMPORTANT**: in this case, the real number of events stored per aggregate is 1023, due to the register length constraint already mentioned.

#### **Event Data Format**

The data format provided by the firmware is grouped into aggregates of events. Each aggregate of channels is then grouped into the board aggregate, and finally into block transfer. Those who need to write their own acquisition software must take care of the following sections.

#### Channel Aggregate Data Format for DT5790 series

The Channel Aggregate is composed by the set of Ne events, where Ne is the programmable number of events contained in one aggregate (see the previous section). The structure of the Channel Aggregate of two events (EVENT 0 and EVENT 1) for 720 (DT5790) series is shown in Fig. 2.2, where:

FI: if 1, the second word is the Format Info

DT: Dual trace enabled flag (1 = enabled, 0 = disabled)

EQ: Charge enabled flag

ET: Time Tag enabled flag

EE: Extras enabled flag.

ES: Waveform (samples) enabled flag

EP: Pedestal enabled flag

Trg Md: Trigger Mode enabled flag

EET: Enable Extended Time Stamp flag. When enabled the extended time stamp is written in the EXTRAS word, according to the options of the EE flag.



Note: to enable the Extended Time Stamp word set bit[7] of register 0x1n80..

DP3: Digital Virtual Probe 3 selection among:

#### "CHANNEL AGGREGATE" DATA FORMAT

31 30 29 28 27 26 2	5 24 23 22 21	20 19	18 17	16 15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	ı	0	BIT						
FI			(	CHANN	EL /	AGGR	EG.	ATE	E SIZE	(in	lwo	rds)	)								SIZE						
DT EQ ET EE ES EP TI	g Md EET [	DP4	DP:	3	NUM SAMPLES WAVE/8										FORMAT												
			TRIGO	ER TI	ΛΕ T	ΓAG																					
DP4 <sub>1</sub> DP3 <sub>1</sub> DP2 <sub>1</sub> DP1 <sub>1</sub>	S <sub>1</sub>			DP	t₀DP3	3₀DP2₀E	P1₀						S	0													
DP4 <sub>3</sub> DP3 <sub>3</sub> DP2 <sub>3</sub> DP1 <sub>3</sub>	S <sub>3</sub>			DP	I₂DP3	3 <sub>2</sub> DP2 <sub>2</sub> D	P12						S	2													
																					EVENT 0						
DP4 <sub>n-1</sub> DP3 <sub>n-1</sub> DP2 <sub>n-1</sub> DP1 <sub>n-1</sub>	S <sub>n-1</sub>					n-2 DP2 <sub>n-2</sub> D	P1 <sub>n-2</sub>						Sr	ı <b>-</b> 2													
				EXTRA	S																						
	Q <sub>LONG</sub>			PU	٦						Qs	HORT	Г							╝							
			TRIGO	SER TII	ΛE 1	ΓAG																					
DP4 <sub>1</sub> DP3 <sub>1</sub> DP2 <sub>1</sub> DP1 <sub>1</sub>	S <sub>1</sub>			DP	t₀DP3	3₀DP2₀E	P1₀						S	0													
DP4 <sub>3</sub> DP3 <sub>3</sub> DP2 <sub>3</sub> DP1 <sub>3</sub>	S <sub>3</sub>			DP	I₂DP3	3 <sub>2</sub> DP2 <sub>2</sub> D	P1 <sub>2</sub>						S	2							_						
																					EVENT 1						
DP4 <sub>n-1</sub> DP3 <sub>n-1</sub> DP2 <sub>n-1</sub> DP1 <sub>n-1</sub>	S <sub>n-1</sub>	·		DP4	DP3 <sub>n</sub>	n-2 DP2 <sub>n-2</sub> D	P1 <sub>n-2</sub>						Sr	-2													
				EXTRA	s																						
	Q <sub>LONG</sub>			PU	R						Qs	HOR	Г														

Fig. 2.2: Channel Aggregate Data Format scheme for DT5790 series.

000 = "External TRG", the external trigger signal when enabled;

001 = "Over Threshold", digital signal that is 1 when the input signal is over the requested threshold;

010 = "Shaped TRG", logic signal generated by a channel in correspondence with its local self- trigger. It is used to propagate the trigger to the other channels of the board and to other external boards, as well as to feed the coincidence trigger logic (refer to [RD2]);

011 = "TRG Val. Acceptance Win.", logic signal corresponding to the time window where the coincidence validation is accepted. The validation enables the event dump into the memory (see [RD2]);

100 = "Pile Up", logic pulse set to 1 when a pile up event occurred (to be implemented);

101 = "Coincidence", logic pulse set to 1 when a coincidence occurred (refer to [RD2]).

DP4: Digital Virtual Probe 4 selection among:

000 = "Short Gate";

001 = "Over Threshold", digital signal that is 1 when the input signal is over the requested threshold;

010 = "TRG Validation", digital signal that is 1 when a coincidence validation signal comes from the mother board FPGA(refer to [RD2]);

011 = "TRG HoldOff", logic signal generated by a channel in correspondence with its local self-trigger. Other triggers are inhibited for the overall Trigger Hold-Off duration;

100 = "Pile Up", logic pulse set to 1 when a pile up event occurred (to be implemented);

101 = "Coincidence", logic pulse set to 1 when a coincidence occurred (refer to [RD2]).

NUM SAMPLES WAVE/8 corresponds to the number of words to be read in the event related to the waveform / 4 (2 samples per word)

DPi<sub>m</sub> (i=1, ...,4; m=0, 1, ...,n-1): Digital Virtual Probe value i for sample m

 $\mathsf{DP1}_m$  is always the "Trigger" probe value

 $\mathsf{DP2}_m$  is always the "Long Gate" probe value

DP3<sub>m</sub> is the value of the probe written in DP3 flag

DP4<sub>m</sub> is the value of the probe written in DP4 flag

 $S_{m'}$  (m'=0, 2, 4, ..., n-2): Even Samples of input signal at time t=m'. If DT=1,  $S_{m'}$  corresponds to the Baseline at time t=m'+1

 $S_{m''}$  (m"=1, 3, 5, ..., n-1): Odd Samples of input signal at time t=m"s

EXTRAS: According to the value of EET, the EXTRAS word is read as follows:



**Note**: when the "**Dual Trace**" option is enabled half of the samples are used to store the baseline. Therefore only the remaining half samples are used for the input waveform. In the plot visualization each input sample is duplicated to keep the same granularity. Those who need to acquire waveforms with full resolution should disable the dual trace option. In CoMPASS select the "NONE" option for "Analog Probe 2" (refer to **[RD3]** for more details).

If EET = 0, EXTRAS[15] = memory full flag; EXTRAS[11:0] = Baseline.

If EET = 1, EXTRAS[15] = memory full flag; EXTRAS[14:0] = Extended Time Stamp, corresponding to the most significant bits of the Time stamp. The time stamp therefore becomes a 32 + 15 = 47 bit number.



Note: to enable the "EXTRAS" word set bit[17] of register 0x8000.

 $Q_{\text{short/long}}$ : integrated charge value in the short/long gate

#### **Board Aggregate Data Format**

For each readout request (occurring when at least one channel has available data to be read) the "interface FPGA (ROC)" reads one aggregate from each enabled channel memory. No more than one aggregate per channel is read each time. The sample of Channel Aggregates is the Board Aggregate. If one channel has no data, that channel does not come into the Board Aggregate. The data format when the two channels of DT5790 have available data is as shown in Fig. **2.3** for DT5790 series:

#### "BOARD AGGREGATE" DATA FORMAT for DT5790 series

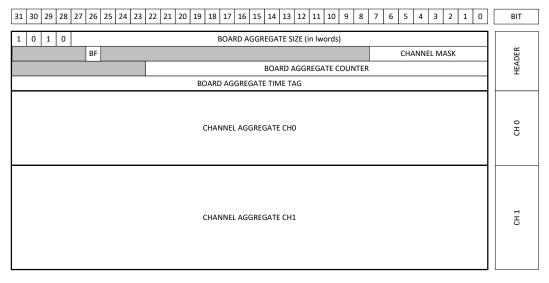


Fig. 2.3: Board Aggregate Data Format scheme for DT5790 series.

BOARD AGGREGATE SIZE: total size of the aggregate

BF: Board Fail flag. This bit is set to "1" because of a hardware problem, as for example the PLL unlock. The user can investigate the problem checking the Board Failure Status register 0x8178, or contacting CAEN support (refer to Chapter **Technical Support**).



**Note**: BF bit is meaningful only for ROC FPGA firmware revision greater than 4.5. It is reserved for previous releases.

CHANNEL MASK: corresponds to those channels participating to the Board Aggregate;
BOARD AGGREGATE COUNTER: counts the board aggregate. It increases with the increase of board aggregates;
BOARD AGGREGATE TIME TAG: is the time of creation of the aggregate (this does not correspond to any physical quantity).

#### Data Block

The readout of the digitizer is done using the Block Transfer (BLT, refer to [RD1]); for each transfer, the board gives a certain number of Board Aggregates, consisting in the Data Block. The maximum number of aggregates that can be transferred in a BLT is defined by the Aggregate Number per BLT. In the final readout each Board Aggregate comes successively. In case of n Board Aggregates, the Data Block is as in Fig. **2.4** 

#### DATA BLOCK

BOARD AGGREGATE 0
BOARD AGGREGATE 1
BOARD AGGREGATE n-1

Fig. 2.4: Data Block scheme.

# 3 Technical Support

CAEN makes available the technical support of its specialists for requests concerning the software and hardware. Use the support form available at the following link:

https://www.caen.it/support-services/support-form/





#### **Electronic Instrumentation**



CAEN SpA is acknowledged as the only company in the world providing a complete range of High/Low Voltage Power Supply systems and Front-End/Data Acquisition modules which meet IEEE Standards for Nuclear and Particle Physics. Extensive Research and Development capabilities have allowed CAEN SpA to play an important, long term role in this field. Our activities have always been at the forefront of technology, thanks to years of intensive collaborations with the most important Research Centres of the world. Our products appeal to a wide range of customers including engineers, scientists and technical professionals who all trust them to help achieve their goals faster and more effectively.



CAEN S.p.A.
Via Vetraia, 11
55049 Viareggio
Italy
Tel. +39.0584.388.398
Fax +39.0584.388.959
info@caen.it
www.caen.it

CAEN GmbH

Eckehardweg 10

42653 Solingen

Germany

Tel. +49.212.2544077

Mobile +49(0)15116548484

Fax +49.212.2544079

info@caen-de.com

www.caen-de.com

CAEN Technologies, Inc. 1140 Bay Street - Suite 2 C Staten Island, NY 10305 USA Tel. +1.718.981.0401 Fax +1.718.556.9185 info@caentechnologies.com www.caentechnologies.com





### **Electronic Instrumentation**

UM5416 - DT5790 DPP-PSD User Manual rev. 1 - May 5<sup>th</sup>, 2020

00117-10-DGT28-MUT)

 $Copyright @ \textit{CAEN SpA. All rights reserved. Information in this publication supersedes all earlier versions. Specifications subject to change without notice. \\$